SN54ALS153, SN74ALS153, SN74AS153 DUAL 1-OF-4 DATA SELECTORS/MULTIPLEXERS

SDAS206A - APRIL 1982 - REVISED DECEMBER 1994

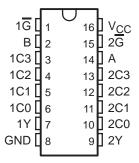
- Permit Multiplexing From n Lines to One Line
- Perform Parallel-to-Serial Conversion
- Strobe (Enable) Line Provided for Cascading (n Lines to n Lines)
- 'ALS253 and SN74AS253A Are 3-State Versions of These Parts
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

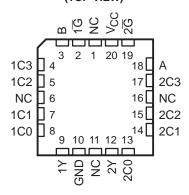
These dual 1-of-4 data selectors/multiplexers contain inverters and drivers to supply full binary decoding data selection to the AND-OR gates. Separate strobe (\overline{G}) inputs are provided for each of the two 4-line sections.

The SN54ALS153 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74ALS153 and SN74AS153 are characterized for operation from 0°C to 70°C.

SN54ALS153 . . . J PACKAGE SN74ALS153, SN74AS153 . . . D OR N PACKAGE (TOP VIEW)



SN54ALS153...FK PACKAGE (TOP VIEW)



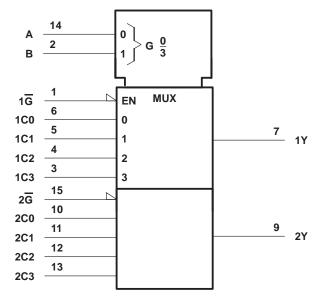
NC - No internal connection

FUNCTION TABLE

		INP		OTDODE	CUITDUIT		
SEL	ECT		DA	TΑ	STROBE G	OUTPUT	
В	Α	C0	C1	C2	C3	Ŭ	·
Х	X	Χ	Χ	Х	X	Н	L
L	L	L	Χ	X	X	L	L
L	L	Н	Χ	Χ	Χ	L	Н
L	Н	Х	L	Χ	Χ	L	L
L	Н	Χ	Н	Χ	Χ	L	Н
Н	L	Χ	Χ	L	Χ	L	L
Н	L	Χ	Χ	Н	Χ	L	Н
Н	Н	Х	Χ	Χ	L	L	L
Н	Н	Χ	Χ	Χ	Н	L	Н

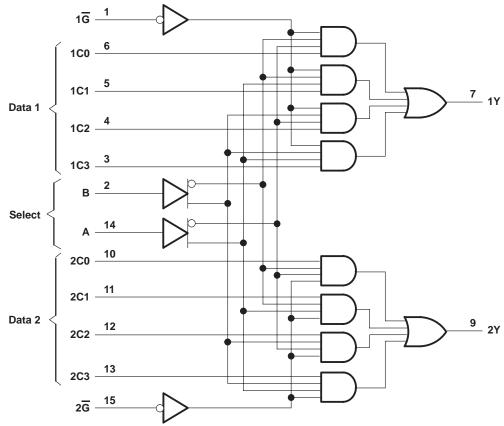
Select inputs A and B are common to both sections.

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.



SN54ALS153, SN74ALS153, SN74AS153 DUAL 1-OF-4 DATA SELECTORS/MULTIPLEXERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

recommended operating conditions

		SN54ALS153			SN	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.7			8.0	V
IOH	High-level output current			-1			-2.6	mA
loL	Low-level output current			12			24	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEGT CONDITIONS				SN	53		
PARAMETER	TEST C	TEST CONDITIONS					TYP‡	MAX	UNIT
VIK	$V_{CC} = 4.5 \text{ V},$	$I_1 = -18 \text{ mA}$			-1.5			-1.5	V
	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	!		V _{CC} -2)		
Vон	V 45V	I _{OH} = -1 mA	2.4	3.3					V
	V _{CC} = 4.5 V	$I_{OH} = -2.6 \text{ mA}$				2.4	3.2		
V	V 45V	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 24 mA					0.35	0.5	V
lį	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
lН	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
Ι _Ι L	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.1			-0.1	mA
ΙΟ [§]	$V_{CC} = 5.5 V$,	V _O = 2.25 V	-20		-112	-30		-112	mA
Icc	$V_{CC} = 5.5 V$,	All inputs at 4.5 V		7.5	14		7.5	14	mA

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

SN54ALS153, SN74ALS153, SN74AS153 DUAL 1-OF-4 DATA SELECTORS/MULTIPLEXERS

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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CL	V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R_L = 500 Ω , T_A = MIN to MAX [†]						
	, - ,	(1111)	SN54A	LS153	SN74A	LS153				
			MIN	MAX	MIN	MAX				
^t PLH	A D	V	5	29	5	21				
^t PHL	A or B	Υ	5	27	5	21	ns			
^t PLH	Data	Y	3	15	3	10				
^t PHL	(any C)		2	18	4	15	ns			
^t PLH	G	V	5	27	5	18	ne			
^t PHL	g	T T	3	22	5	18	ns			

T For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Operating free-air temperature range, T _A : SN74AS153 0	°C to 70°C
Storage temperature range –65°	C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN	SN74AS153		
		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
V _{IL}	Low-level input voltage			0.8	V
ІОН	High-level output current			-15	mA
loL	Low-level output current			48	mA
T_A	Operating free-air temperature	0		70	°C

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				SI	N74AS15	i3	
	PARAMETER	TEST CONE	DITIONS	MIN	TYP [†]	MAX	UNIT
٧ıK		$V_{CC} = 4.5 \text{ V},$	I _I = –18 mA			-1.2	V
.,		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	I _{OH} = -2 mA	VCC -2	2		
VOH		V _{CC} = 4.5 V,	I _{OH} = -15 mA	2.4	3.2		V
VOL		V _{CC} = 4.5 V,	I _{OL} = 48 mA		0.35	0.5	V
	A, B	V 55V				0.2	4
Ц	All others	$V_{CC} = 5.5 \text{ V},$	V _I = 7 V			0.1	mA
	A, B	V 55V	V 0.7.V			40	
lн	All others	$V_{CC} = 5.5 \text{ V},$	$V_{I} = 2.7 \text{ V}$			20	μΑ
	A, B	V 55V				-1	
ΊL	All others	$V_{CC} = 5.5 V,$	$V_{I} = 0.4 V$			-0.5	mA
l _O ‡		V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	mA
ICCH		V _{CC} = 5.5 V			16	26	mA
ICCL		V _{CC} = 5.5 V			21	33	mA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

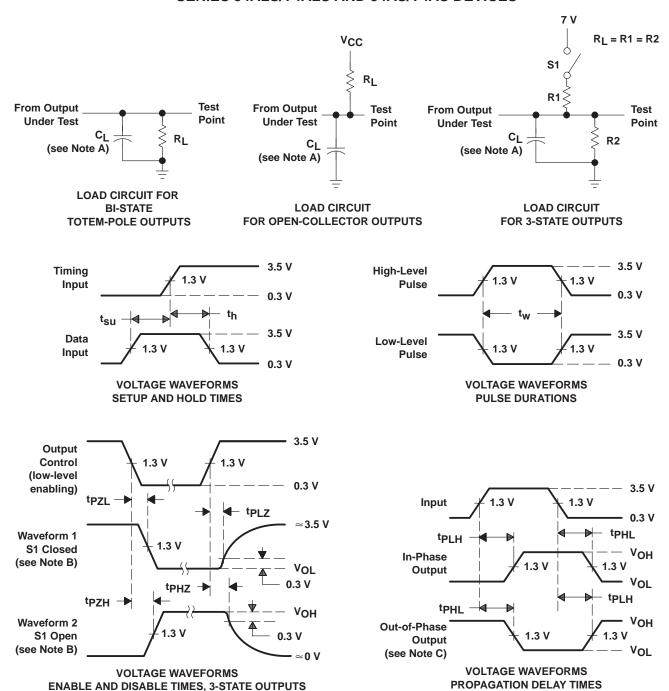
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 C _L = 50 p R _L = 500 T _A = MIN	UNIT	
			MIN	MAX	
^t PLH	A an B	V	3	12.5	
^t PHL	A or B	Y	3	11	ns
^t PLH	Data	V	2	7	
^t PHL	(any C)	Y	2	8	ns
^t PLH	G	٧	3	11.5	20
^t PHL	G	f	10	9	ns

[§] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 - D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_f = t_f = 2$ ns, duty cycle = 50%.
 - E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
8413401EA	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8413401EA SNJ54ALS153J	Samples
8413401FA	ACTIVE	CFP	W	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8413401FA SNJ54ALS153W	Samples
SN54ALS153J	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54ALS153J	Samples
SN74ALS153DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS153	Samples
SN74ALS153N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS153N	Samples
SN74ALS153NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS153	Samples
SN74AS153N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74AS153N	Samples
SN74AS153NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS153	Samples
SNJ54ALS153J	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8413401EA SNJ54ALS153J	Samples
SNJ54ALS153W	ACTIVE	CFP	W	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8413401FA SNJ54ALS153W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

PACKAGE OPTION ADDENDUM

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- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ALS153, SN74ALS153:

Catalog: SN74ALS153

Military: SN54ALS153

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

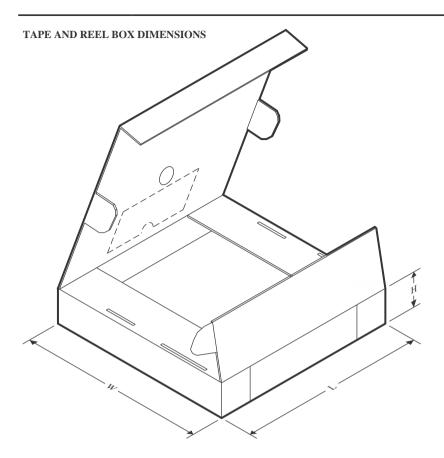


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS153DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74ALS153NSR	so	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS153NSR	so	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS153DR	SOIC	D	16	2500	340.5	336.1	32.0
SN74ALS153NSR	SO	NS	16	2000	356.0	356.0	35.0
SN74AS153NSR	so	NS	16	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
8413401FA	W	CFP	16	25	506.98	26.16	6220	NA
SN74ALS153N	N	PDIP	16	25	506	13.97	11230	4.32
SN74ALS153N	N	PDIP	16	25	506	13.97	11230	4.32
SN74AS153N	N	PDIP	16	25	506	13.97	11230	4.32
SN74AS153N	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54ALS153W	W	CFP	16	25	506.98	26.16	6220	NA

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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